The XPand1201 is a low-cost, flexible, development platform. This platform supports up to ten 1.0 in. or 0.8 in. pitch conduction-cooled CompactPCI modules. It provides 482 W of total simultaneous power, which can be distributed as up to 16 A on 12 V, up to 40 A on 5 V, and up to 20 A on 3.3 V. The heat from the internal conduction-cooled modules is conducted to sidewall exchangers, where it is dissipated to the ambient environment by forced-air cooling. This efficient thermal design allows up to 60 W of power dissipation per slot at 30°C ambient, while maintaining 70°C at the module’s thermal interface.

X-ES platforms, including the XPand1201, provide a feature-rich solution for system development. RTMs provide maximum I/O flexibility and rapid system prototyping. Power and reset LEDs are provided for system status. A momentary push button is provided for reset, and a switch is provided for DC power enable.

The XPand1201 is available for purchase in several rapid-development, standard configurations. Custom configurations of modules, RTMs, and backplanes are also available utilizing X-ES and third party components.
**Form Factor**
- 3U CompactPCI 1.0 in. or 0.8 in. pitch
- 3U CompactPCI RTM

**Slots**
- Ten 1.0 in. pitch slots (including power supply slots)
- Eight 1.0 in. pitch RTM slots

**Power**
- 110–240 VAC, 50/60 Hz power input
- 482 W total simultaneous power
- Up to 16 A on 12 V
- Up to 40 A on 5 V
- Up to 20 A on 3.3 V
- Please consult factory for additional power options

**Cooling**
- Up to 60 W per slot at 30°C ambient and 70°C rail

**Physical Characteristics**
- 16.5 in. (H), x 5.5 in. (W), x 11.5 in. (L)
- 20 lbs. with backplane and power supply

---

**XPand1201 Platform**

---

Copyright © 2014 Extreme Engineering Solutions, Inc. (X-ES). All rights reserved. Specifications are subject to change without notice. All trademarks are property of their respective owners.

www.xes-inc.com